- **Meets or Exceeds the Requirements of ANSI EIA/TIA-232-E and ITU Recommendation V.28**
- **10-mA Current Limited Output**
- **Wide Range of Supply Voltage**
  V_{CC} = 4.5 V to 15 V
- **Low Power . . . 130 mW**
- **Built-In 5-V Regulator**
- **Response Control Provides:**
  Input Threshold Shifting
  Input Noise Filtering
- **Power-Off Output Resistance . . . 300 Ω Typ**
- **Driver Input TTL Compatible**

D OR P PACKAGE
TOP VIEW

```
         ┌───∪───┐
V_CC- [  1     8  ] V_CC+
  DA  [  2     7  ] DY
  RY  [  3     6  ] RTC
 GND  [  4     5  ] RA
         └───────┘
```
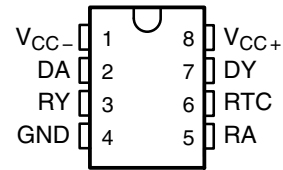
description

The SN75155 monolithic line driver and receiver is designed to satisfy the requirements of the standard interface between data terminal equipment and data communication equipment as defined by ANSI EIA/TIA-232-E. A response control input is provided for the receiver. A resistor or a resistor and a bias voltage can be connected between the response control input and ground to provide noise filtering. The driver used is similar to the SN75188. The receiver used is similar to the SN75189A.
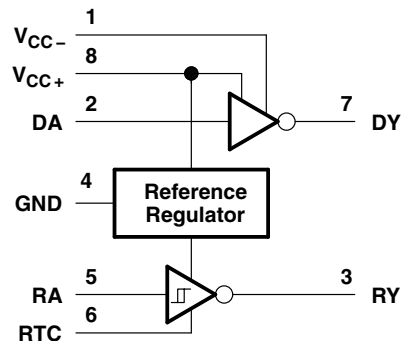
The SN75155 is characterized for operation from 0°C to 70°C.

logic symbol†
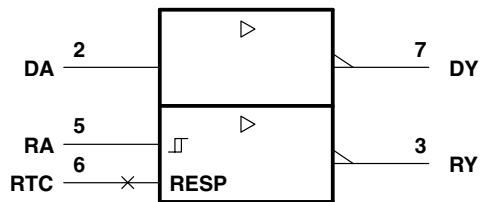
† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12

logic diagram

TEXAS INSTRUMENTS

schematic

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC+} (see Note 1) .... 15 V
Supply voltage, V_{CC-} (see Note 1) .... −15 V
Input voltage range, V_I: Driver .... −15 V to 15 V
                        Receiver .... −30 V to 30 V
Output voltage range (driver), V_O .... −15 V to 15 V
Continuous total power dissipation .... See Dissipation Rating Table
Operating free-air temperature range, T_A .... 0°C to 70°C
Storage temperature range, T_{stg} .... −65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds .... 260°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1:   All voltage values are with respect to network ground terminal.

DISSIPATION RATING TABLE

PACKAGE	$T_A \leq 25°C$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25°C$	$T_A = 70°C$ POWER RATING
D	725 mW	5.8 mW/°C	464 mW
P	1000 mW	8.0 mW/°C	640 mW

TEXAS
INSTRUMENTS

POST OFFICE BOX 655303 ● DALLAS, TEXAS 75265

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V_{CC+}	4.5	12	15	V
Supply voltage, V_{CC-}	−4.5	−12	−15	V
Output voltage, driver, $V_{O(D)}$			±15	V
Input voltage, receiver, $V_{I(R)}$	−25		25	V
High-level input voltage, driver, V_{IH}	2			V
Low-level input voltage, driver, V_{IL}			0.8	V
Response control current			±5.5	mA
Output current, receiver, $I_{O(R)}$			24	mA
Operating free-air temperature, T_A	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

total device

PARAMETER		TEST CONDITIONS			MIN	TYP[†]	MAX	UNIT
I_{CCH+}	High-level supply current	V_{CC+} = 5 V,	V_{CC-} = −5 V	$V_{I(D)}$ = 2 V, $V_{I(R)}$ = 2.3 V, Output open		6.3	8.1	mA
		V_{CC+} = 9 V,	V_{CC-} = −9 V			9.1	11.9	
		V_{CC+} = 12 V,	V_{CC-} = −12 V			10.4	14	
I_{CCL+}	Low-level supply current	V_{CC+} = 5 V,	V_{CC-} = −5 V	$V_{I(D)}$ = 0.8 V, $V_{I(R)}$ = 0.6 V, Output open		2.5	3.4	mA
		V_{CC+} = 9 V,	V_{CC-} = −9 V			3.7	5.1	
		V_{CC+} = 12V,	V_{CC-} = −12 V			4.1	5.6	
I_{CC+}	Supply current	V_{CC+} = 5 V,	V_{CC-} = 0	$V_{I(R)}$ = 2.3 V, $V_{I(D)}$ = 0		4.8	6.4	mA
		V_{CC+} = 9 V,	V_{CC-} = 0			6.7	9.1	
I_{CCH-}	High-level supply current	V_{CC+} = 5 V,	V_{CC-} = −5 V	$V_{I(D)}$ = 2 V, $V_{I(R)}$ = 2.3 V Output open		−2.4	−3.1	mA
		V_{CC+} = 9 V,	V_{CC-} = −9 V			−3.9	−4.9	
		V_{CC+} = 12 V,	V_{CC-} = −12 V			−4.8	−6.1	
I_{CCL-}	Low-level supply current	V_{CC+} = 5 V,	V_{CC-} = −5 V	$V_{I(D)}$ = 0.8 V, $V_{I(R)}$ = 0.6 V, Output open		−0.2	−0.35	mA
		V_{CC+} = 9 V,	V_{CC-} = −9 V			−0.25	−0.4	
		V_{CC+} = 12 V,	V_{CC-} = −12 V			−0.27	−0.45	

[†] All typical values are at T_A = 25°C.

electrical characteristics over recommended operating free-air temperature range, V_{CC+} = 12 V, V_{CC-} = −12 V (unless otherwise noted)

driver section

PARAMETER		TEST CONDITIONS			MIN	TYP†	MAX	UNIT
V_{OH}	High-level output voltage	V_{IL} = 0.8 V, R_L = 3 kΩ	V_{CC+} = 5 V,	V_{CC-} = −5 V	3.2	3.7		V
			V_{CC+} = 9 V,	V_{CC-} = −9 V	6.5	7.2		
			V_{CC+} = 12 V,	V_{CC-} = −12 V	8.9	9.8		
V_{OL}	Low-level output voltage (see Note 2)	V_{IH} = 2 V, R_L = 3 kΩ	V_{CC+} = 5 V,	V_{CC-} = −5 V		−3.6	−3.2	V
			V_{CC+} = 9 V,	V_{CC-} = −9 V		−7.1	−6.4	
			V_{CC+} = 12 V,	V_{CC-} = −12 V		−9.7	−8.8	
I_{IH}	High-level input current	V_I = 7 V					5	µA
I_{IL}	Low-level input current	V_I = 0				−0.73	−1.2	mA
$I_{OS(H)}$	High-level short-circuit output current	V_I = 0.8 V, V_O = 0			−7	−12	−14.5	mA
$I_{OS(L)}$	Low-level short-circuit output current	V_I = 2 V, V_O = 0			6.5	11.5	15	mA
r_O	Output resistance with power off	V_O = −2 V to 2 V				300		Ω

receiver section (see Figure 1)

PARAMETER		TEST CONDITIONS			MIN	TYP†	MAX	UNIT
V_{IT+}	Positive-going input threshhold voltage				1.2	1.9	2.3	V
V_{IT-}	Negative-going input threshhold voltage				0.6	0.95	1.2	V
V_{hys}	Hystresis voltage (V_{IT+} − V_{IT-})				0.6			V
$V_{O(H)}$	High-level output voltage	V_I = 0.6 V, I_{OH} = 10 µA	V_{CC+} = 5 V,	V_{CC-} = −5 V	3.7	4.1	4.5	V
			V_{CC+} = 12 V,	V_{CC-} = −12 V	4.4	4.7	5.2	
		V_I = 0.6 V, I_{OH} = 0.4 mA	V_{CC+} = 5 V,	V_{CC-} = −5 V	3.1	3.4	3.8	
			V_{CC+} = 12 V,	V_{CC-} = −12 V	3.6	4	4.5	
$V_{O(L)}$	Low-level output voltage	V_I = 2.3 V,	I_{OL} = 24 mA			0.2	0.3	V
I_{IH}	High-level input current	V_I = 25 V			3.6	6.7	10	mA
		V_I = 3 V			0.43	0.67	1	mA
I_{IL}	Low-level input current	V_I = −25 V			−3.6	−6.7	−10	mA
		V_I = −3 V			−0.43	−0.67	−1	mA
I_{OS}	Short-circuit output current	V_I = 0.6 V				−2.8	−3.7	mA

† All typical values are at T_A = 25°C.

NOTE 2: The algebraic limit system, in which the more positive (less negative) limit is designated as maximum, is used in this data sheet for logic voltage levels only (e.g., if −8.8 V is the maximum, the typical value is a more negative value).

switching characteristics over recommended operating free-air temperature range, V_{CC+} = 5 V, V_{CC-} = – 5 V, C_L = 50 pF (unless otherwise noted)

driver section (see Figure 2)

	PARAMETER	TEST CONDITIONS		MIN	TYP†	MAX	UNIT
t_{PLH}	Propagation delay time, low- to high level output	R_L = 3 kΩ			250	480	ns
t_{PHL}	Propagation delay time, high- to low level output				80	150	
t_r	Output rise time	R_L = 3 kΩ			67	180	ns
		R_L = 3 kΩ to 7 kΩ,	C_L = 2500 pF		2.4	3	μs
t_f	Output fall time	R_L = 3 kΩ			48	160	ns
		R_L = 3 kΩ to 7 kΩ,	C_L = 2500 pF		1.9	3	μs

receiver section (see Figure 3)

	PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
t_{PLH}	Propagation delay time, low- to high level output	R_L = 400 Ω		175	245	ns
t_{PHL}	Propagation delay time, high- to low level output			37	100	
t_r	Output rise time	R_L = 400 Ω		255	360	ns
t_f	Output fall time	R_L = 400 Ω		23	50	ns

† All typical values are at T_A = 25°C.

PARAMETER MEASUREMENT INFORMATION
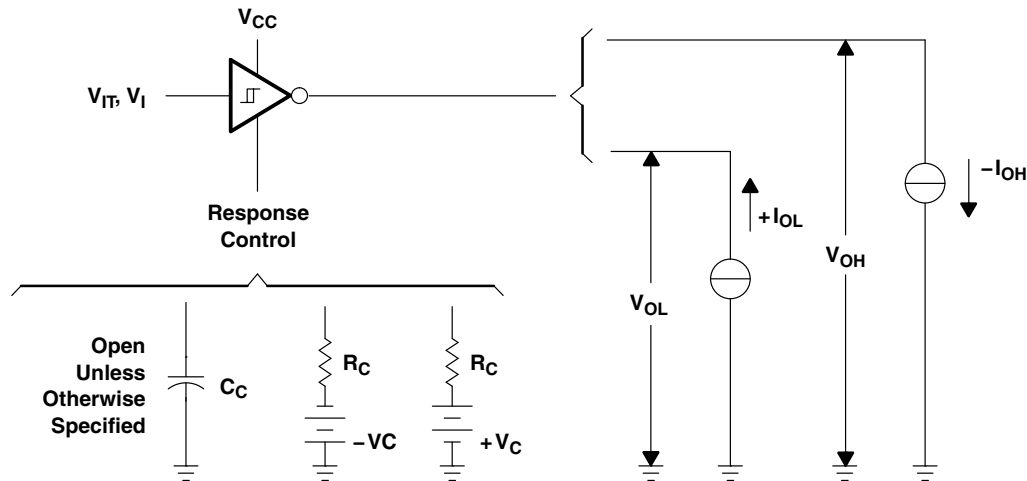
Figure 1. Receiver Section Test Circuit (V_{IT+}, V_{IT-}, V_{OH}, V_{OL})

PARAMETER MEASUREMENT INFORMATION

TEST CIRCUIT
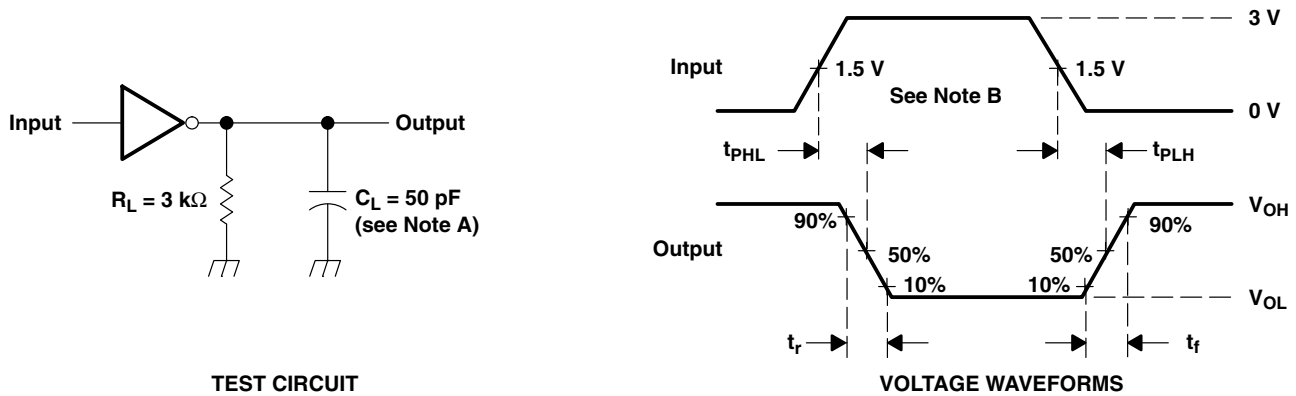
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
   B. The input waveform is supplied by a generator with the following characteristics: $Z_O = 50\ \Omega$, $t_w = 1\ \mu s$, $t_r \leq 10$ ns, $t_f \leq 10$ ns.

Figure 2. Driver Section Switching Test Circuit and Voltage Waveforms
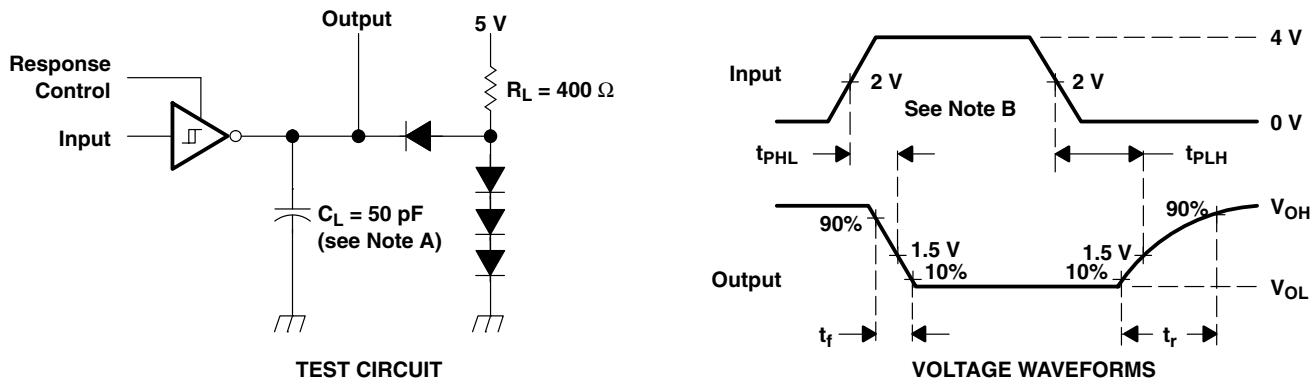
TEST CIRCUIT

VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
   B. The input waveform is supplied by a generator with the following characteristics: $Z_O = 50\ \Omega$, $t_w = 1\ \mu s$, $t_r \leq 10$ ns, $t_f \leq 10$ ns.

Figure 3. Receiver Section Switching Test Circuit and Voltage Waveforms
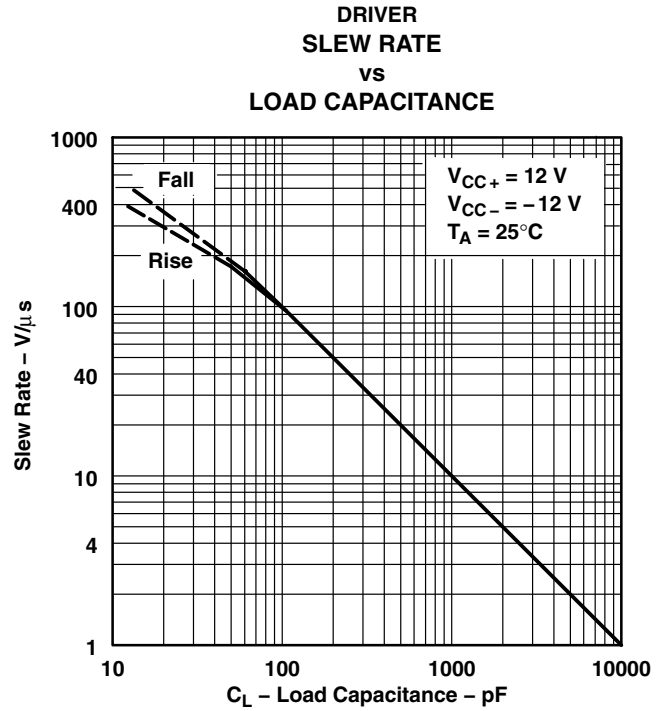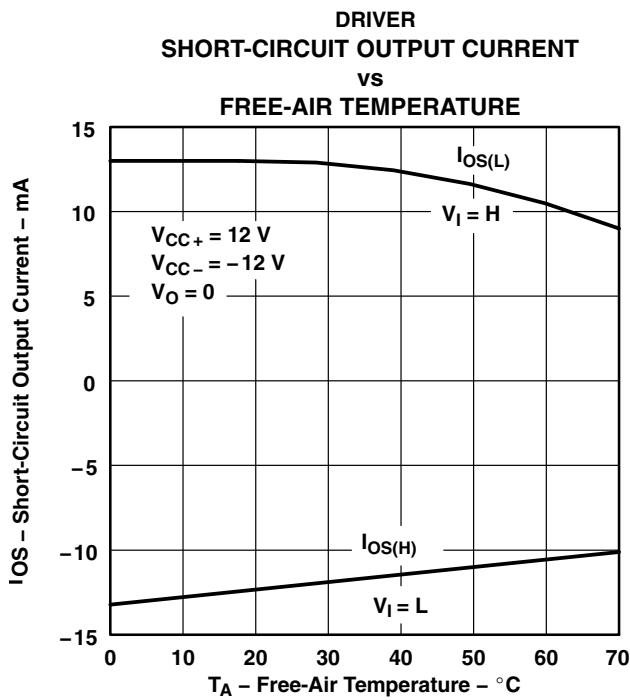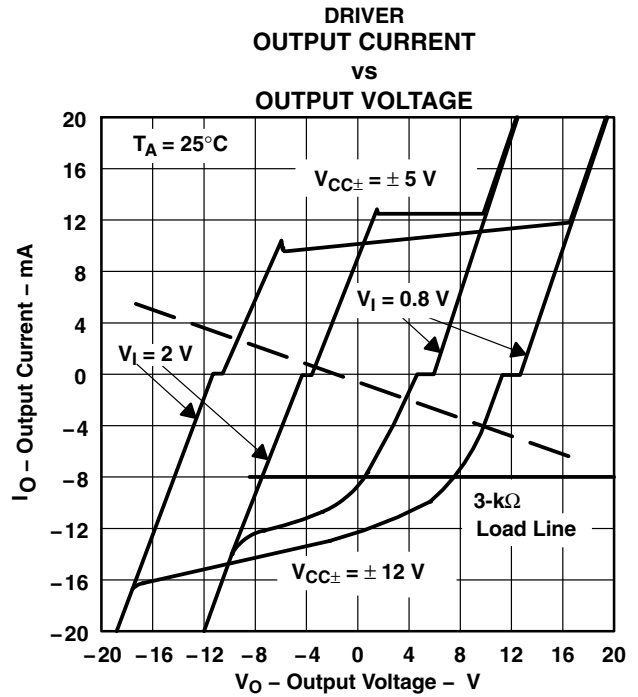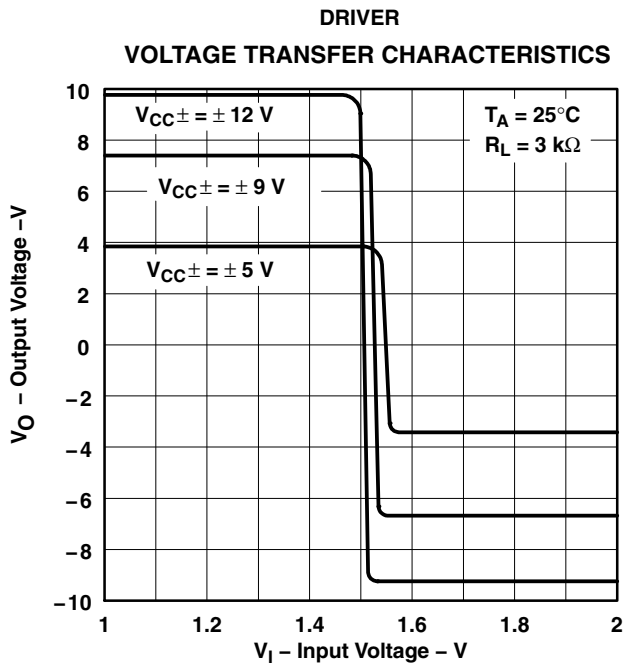
TEXAS
INSTRUMENTS
POST OFFICE BOX 655303 ● DALLAS, TEXAS 75265

TYPICAL CHARACTERISTICS
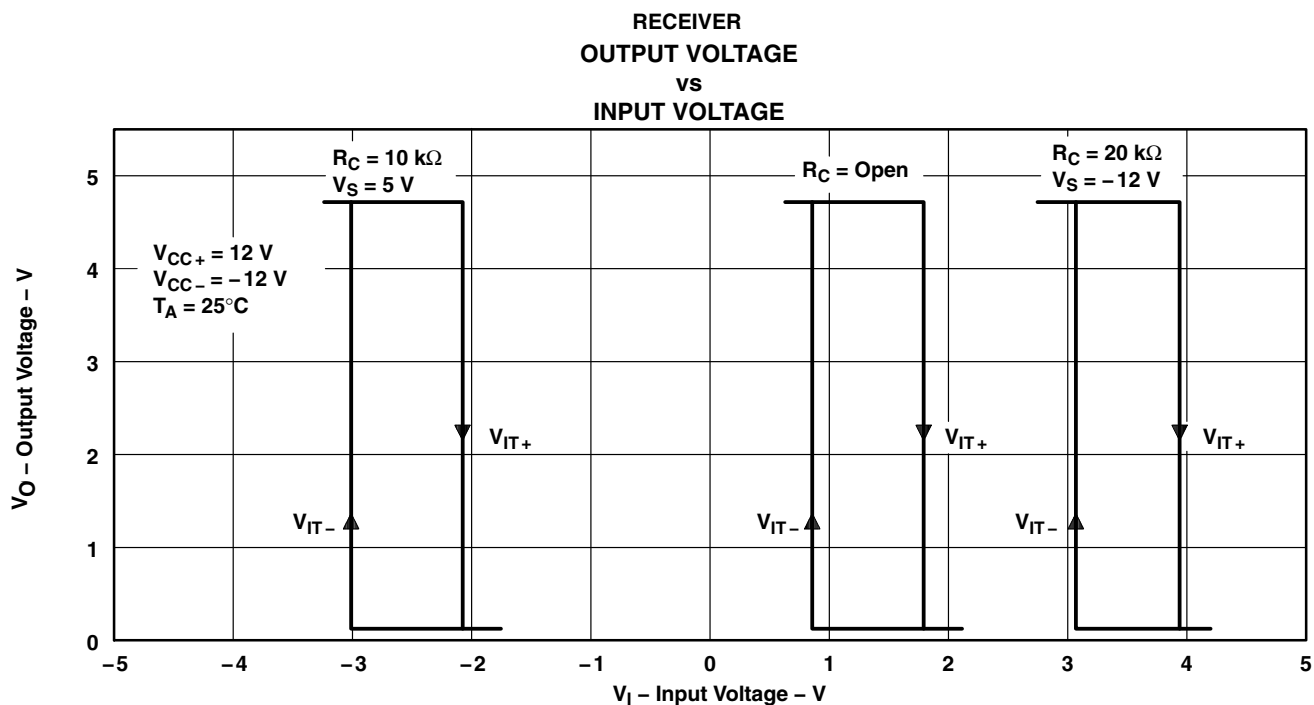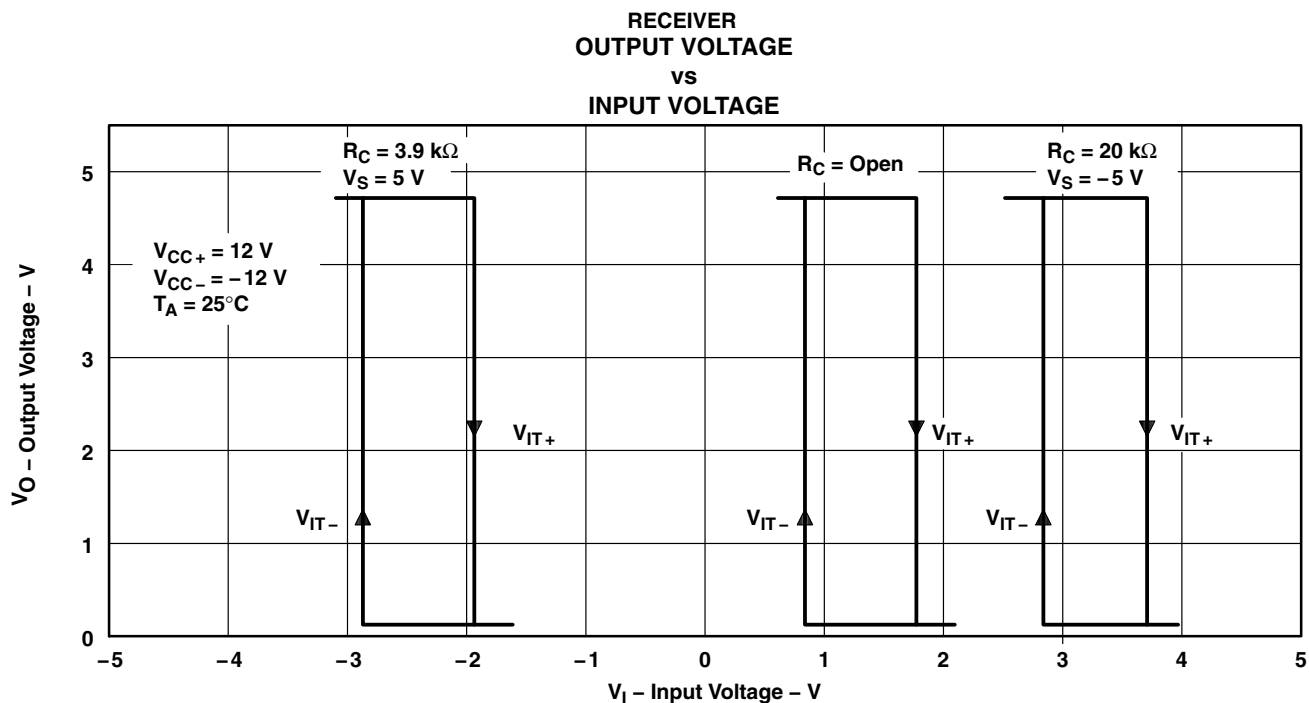
DRIVER
VOLTAGE TRANSFER CHARACTERISTICS

Figure 4

DRIVER
OUTPUT CURRENT
vs
OUTPUT VOLTAGE

Figure 5

DRIVER
SHORT-CIRCUIT OUTPUT CURRENT
vs
FREE-AIR TEMPERATURE

Figure 6

DRIVER
SLEW RATE
vs
LOAD CAPACITANCE

Figure 7

TYPICAL CHARACTERISTICS

**RECEIVER
OUTPUT VOLTAGE
vs
INPUT VOLTAGE**

Figure 8

**RECEIVER
OUTPUT VOLTAGE
vs
INPUT VOLTAGE**

Figure 9

POST OFFICE BOX 655303 ● DALLAS, TEXAS 75265

TYPICAL CHARACTERISTICS

RECEIVER
INPUT THRESHOLD VOLTAGE
vs
FREE-AIR TEMPERATURE

V_{CC+} = 12 V
V_{CC-} = −12 V

V_{IT+}

V_{IT-}

Input Threshold Voltage – V

T_A – Free-Air Temperature – °C

Figure 10

RECEIVER
INPUT CURRENT
vs
INPUT VOLTAGE

T_A = 25°C
V_{CC+} = 12 V
V_{CC-} = −12 V

I_I – Input Current – mA

V_I – Input Voltage – V

Figure 11

RECEIVER
NOISE REJECTION

V_{CC+} = 12 V
V_{CC-} = −12 V
T_A = 25°C

C_C = 1000 pF
C_C = 500 pF
C_C = 300 pF
C_C = 100 pF
C_C = 10 pF

Input Threshold Voltage – V

t_W – Pulse Duration – ns

Figure 12

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN75155D	ACTIVE	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	75155	Samples
SN75155DR	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	75155	Samples
SN75155DRE4	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	75155	Samples
SN75155P	ACTIVE	PDIP	P	8	50	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN75155P	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1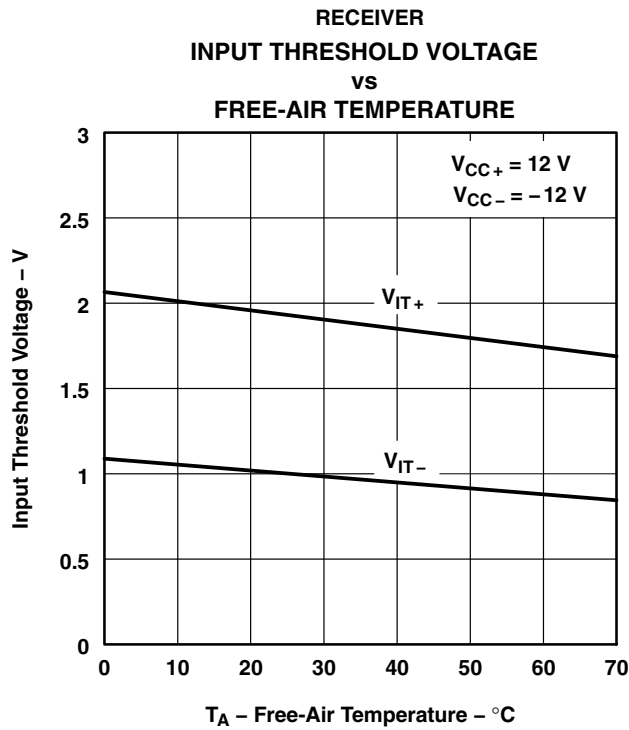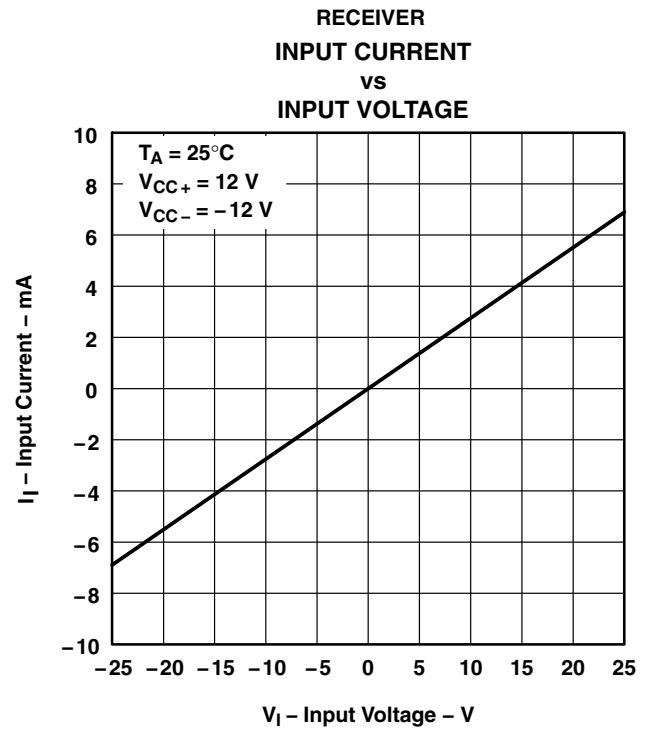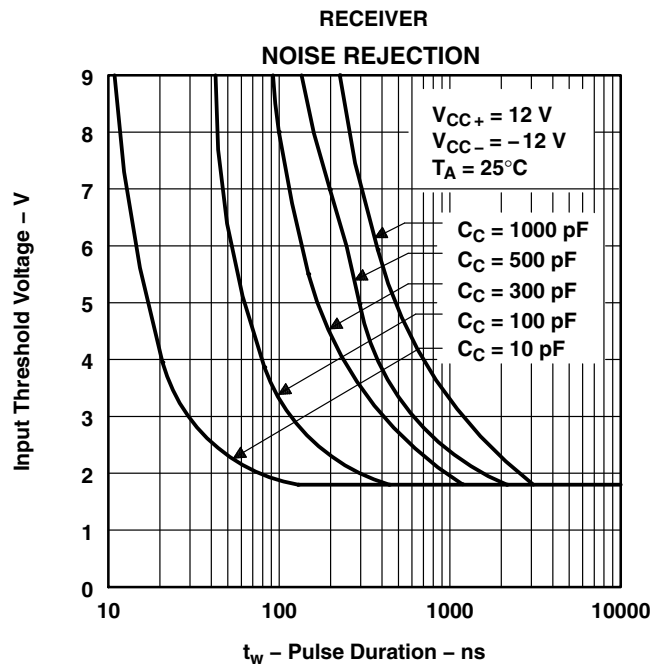% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75155DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

![Texas Instruments]

PACKAGE MATERIALS INFORMATION

TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75155DR	SOIC	D	8	2500	340.5	336.1	25.0

PACKAGE MATERIALS INFORMATION

TUBE

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN75155D	D	SOIC	8	75	507	8	3940	4.32
SN75155P	P	PDIP	8	50	506	13.97	11230	4.32

P (R—PDIP—T8)   PLASTIC DUAL—IN—LINE PACKAGE

0.400 (10,16)
0.355 (9,02)

8   5

0.260 (6,60)
0.240 (6,10)

1   4

0.070 (1,78)
0.045 (1,14)

0.045 (1,14)
0.030 (0,76)

0.020 (0,51) MIN

0.200 (5,08) MAX

Seating Plane

0.125 (3,18) MIN

0.100 (2,54)

0.021 (0,53)
0.015 (0,38)

⊕ 0.010 (0,25) Ⓜ

0.325 (8,26)
0.300 (7,62)

0.015 (0,38)

Gauge Plane

0.010 (0,25) NOM

0.430 (10,92)
MAX

4040082/E   04/2010

NOTES: A.   All linear dimensions are in inches (millimeters).
         B.   This drawing is subject to change without notice.
         C.   Falls within JEDEC MS—001 variation BA.

.228-.244   TYP
[5.80-6.19]

A

PIN 1 ID AREA

1

.189-.197
[4.81-5.00]
NOTE 3

4

B

.150-.157
[3.81-3.98]
NOTE 4

6X .050
[1.27]

8

2X
.150
[3.81]

5

8X .012-.020
[0.31-0.51]

⊕ .010 [0.25] Ⓜ C A B

C

SEATING PLANE

⌒ .004 [0.1] C

4X (0°-15°)

.069 MAX
[1.75]

SEE DETAIL A

4X (0°-15°)

.005-.010   TYP
[0.13-0.25]

.010
[0.25]

0°- 8°

.016-.050
[0.41-1.27]

(.041)
[1.04]

.004-.010
[0.11-0.25]

DETAIL A
TYPICAL

4214825/C   02/2019

NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches.
   Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
   exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.

8X (.061)
[1.55]

SYMM
₵

SEE
DETAILS

1

8

8X (.024)
[0.6]

SYMM
₵

4

(R.002) TYP
[0.05]

5

6X (.050)
[1.27]

(.213)
[5.4]

LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X

METAL

SOLDER MASK
OPENING

SOLDER MASK
OPENING

METAL UNDER
SOLDER MASK

EXPOSED
METAL

EXPOSED
METAL

.0028 MAX
[0.07]
ALL AROUND

.0028 MIN
[0.07]
ALL AROUND

NON SOLDER MASK
DEFINED

SOLDER MASK
DEFINED

SOLDER MASK DETAILS

4214825/C   02/2019

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

8X (.061)
[1.55]

SYMM
℄

1

8X (.024)
[0.6]

8

SYMM
℄

(R.002) TYP
[0.05]

6X (.050)
[1.27]

4

5

(.213)
[5.4]

SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.125 MM] THICK STENCIL
SCALE:8X

4214825/C   02/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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